

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YOUJUN XIONG	06/28/2018
	HONGYU DING	06/28/2018
	HONGBO ZHU	06/28/2018
RECEIVING PARTY DATA		
Name:	UBTECH ROBOTICS CORP	
Street Address:	16TH AND 22ND FLOORS, BLOCK C1, NANSHAN I PARK, NO. 1001 XUEYUAN ROAD, NANSHAN DISTRICT	
City:	SHENZHEN	
State/Country:	CHINA	
Postal Code:	518000	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16059057	
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ATTORNEY DOCKET NUMBER:	2018UBH-A1US013	
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SIGNATURE:	/Raymond J. Chew/	
DATE SIGNED:	08/09/2018	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS Yunjun Xiong; Hongyu Ding; Hongbo Zhu, the assignors, whose mailing address is/are 16th and 22nd Floors, Block C1, Nanshan I Park, No. 1001 Xueyuan Road, Nanshan District, Shenzhen, Guangdong, China,

have invented certain new and useful improvements in an invention relating to and entitled SERVO AND ROBOT HAVING THE SAME, the invention, as fully set forth and described in an application for Letters Patent to be filed at the United States Patent and Trademark Office and naming the assignors as inventors and applicants;

AND WHEREAS UBTECH Robotics Corp. of China, the assignee, whose mailing address is 16th and 22nd Floors, Block C1, Nanshan I Park, No. 1001 Xueyuan Road, Nanshan District, Shenzhen, Guangdong, China,

is desirous of acquiring the entire right, title and interest in and to said invention, and in and to Any Letters Patent that may be obtained therefor;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, receipt of which is hereby acknowledged, the assignors, do hereby confirm that they have sold, assigned and transferred, and do hereby sell, assign and transfer to the assignee the full and exclusive right to the said invention in the United States and their entire right, title and interest for the United States in and to the invention, together with their entire right, title and interest in and to said application, any and all divisional applications thereof, and any and all Letters Patent of the United States which may issue or be reissued for the invention;

AND the assignors hereby authorize and request the Director of the United States Patent and Trademark Office to issue to said assignee of any and all said Letters Patent not already issued as the assignee of their entire right, title and interest in and to the same, for the sole use and benefit of said assignee, its successors, assigns or legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by the assignors had this assignment and sale not been made.

AND the assignors, on behalf of themselves and their executors and administrators, hereby covenant and agree to do all such lawful acts and things and to execute without further consideration such further lawful assignments, documents, assurances, applications, and other instruments as may reasonably be required by said assignee, its successors, assigns or legal representatives, to obtain any and all Letters Patent of the United States for said invention and vest the same in said assignee, its successors, assigns or legal representatives.

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Cont.: Assignment

Younjun Xiong [Signature of Inventor], SIGNED on this [28th] day of [June], 2018
Younjun Xiong

Tongyu Ding [Signature of Inventor], SIGNED on this [28th] day of [June], 2018
Hongyu Ding

Hongbo Zhu [Signature of Inventor], SIGNED on this [28th] day of [June], 2018
Hongbo Zhu

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